

## PATENT ASSIGNMENT

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NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Rajiv K. Mongia	03/16/2007
RECEIVING PARTY DATA	
Name:	Intel Corporation
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11618795
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NAME OF SUBMITTER:	Al AuYeung
Total Attachments: 2 source=P24475_assignment#page1.tif source=P24475_assignment#page2.tif	

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REEL: 019045 FRAME: 0498

## **ASSIGNMENT**

## **PATENT**

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned, **Rajiv K. Mongia**, hereby sells, assigns, and transfers to Intel Corporation, a corporation of Delaware, having a principal place of business at 2200 Mission College Blvd., Santa Clara, California 95052, ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements that are disclosed in the application for the United States Patent No. 11/618,795, filed on December 30, 2006, and is entitled:

### **USING REFRIGERATION AND HEAT PIPE FOR ELECTRONICS COOLING APPLICATIONS**

and in and to said application and all divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original patents, reissued patents, reexamination certificates, and extensions, that have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

agree that said Assignee may apply for and receive a patent or patents for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements, and all applications for

and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenants with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

**Each Inventor: Please Sign and Date Below:**

16 - March, 2007        
Date                              Rajiv K. Mongia